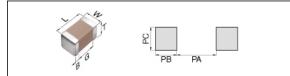


C1608X5R1E225K080AB (TDK item description : C1608X5R1E225KT****)

| Applications | | Commercial Grade |
|--------------|--------------------|---------------------|
| Feature | General | General (Up to 50V) |
| Series | C1608 [EIA CC0603] | |





| Size | | |
|------------------------------|--|-----------------|
| Length(L) | 1.60mm +/-0.10mm | |
| Width(W) | 0.80mm +/-0.10mm | |
| Thickness(T) | 0.80mm +/-0.10mm | |
| Terminal Width(B) | 0.20mm Min. | |
| Terminal Spacing(G) | 0.30mm Min. | |
| Recommended Land Pattern(PA) | 0.70 to 1.00mm (Flow Soldering) 0.60 to 0.80mm (Flow Soldering) | Reflow Solderin |
| Recommended Land Pattern(PB) | 0.80 to 1.00mm (Flow Soldering) 0.60 to 0.80mm (Flow Soldering) | Reflow Solderin |
| Recommended Land Pattern(PC) | 0.60 to 0.80mm (Flow Soldering) 0.60 to 0.80mm (Flow Soldering) | Reflow Solderin |
| Recommended Slit Pattern(SD) | | |

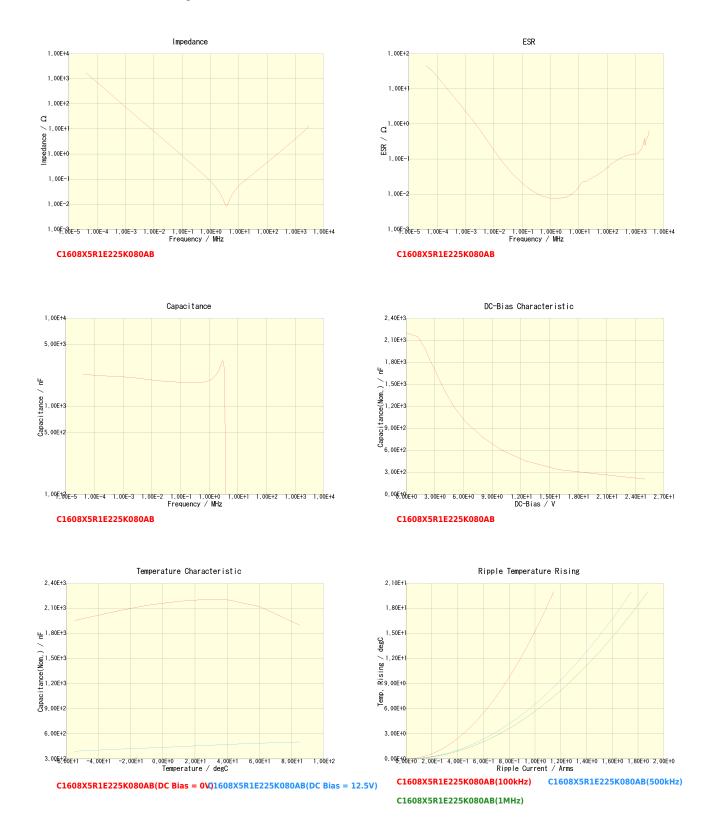
| Electrical Characteristics | | | | |
|----------------------------|--------------|--|--|--|
| Capacitance | 2.2uF +/-10% | | | |
| Rated Voltage | 25Vdc | | | |
| Temperature Characteristic | X5R(+/-15%) | | | |
| Dissipation Factor | 10% Max. | | | |
| Insulation Resistance | 227MΩ Min. | | | |

| Other | | | |
|------------------|------------------------------------|--|--|
| Soldering Method | Reflow, Flow | | |
| AEC Q200 | No | | |
| Packing | Punched (Paper)Taping [180mm Reel] | | |
| Package Quantity | 4000Pcs Min. | | |

•This PDF document was created based on the data listed on the TDK Corporation website. •All specifications are subject to change without notice.

C1608X5R1E225K080AB

Characteristic Graphs (This is reference data, and does not guarantee the product's characteristics.)



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